

MICROELECTRONICS BUSINESS OF IBM

ENABLING MERCHANT PLAYERS TO COMPETE

TABLE OF CONTENTS

i.	Petrov Group License Agreement	
ii.	Table of Contents and List of Figures	
1.	INTRODUCTION	1-8
1.1	Why (and How) We Specialize In IBM Analysis	1-8
1.2	About IBM's PR Machine.....	1-10
1.3	IBM is an Institution.....	1-13
2.	REPORT SCOPE AND METHODOLOGY.....	2-1
2.1	Report Scope	2-1
2.2	Report Methodology.....	2-2
3.	EXECUTIVE SUMMARY.....	3-1
3.1	Fit and Role of Microelectronics within IBM.....	3-3
3.2	New Merchant Market Microelectronics Strategy	3-5
3.3	IBM Silicon Integration Enablement Range	3-8
3.4	Transformation of IBM's Merchant Microelectronics Business (1993 to 2004).....	3-9
3.5	Organizational Structure and Trends	3-10
3.5	Operating Locations and Headcount of the Microelectronics Business	3-12
3.6	Microelectronics Business Performance and Trends	3-14
3.7	Our Revenue Stream Model	3-16
3.8	Microelectronics Revenues of IBM	3-17
3.9	IBM Operates on a New Semiconductor Business Plane.....	3-19
3.10	Transformation of IBM's Semiconductors Customer Base	3-21
4.	MICROELECTRONICS FIT AND ROLE WITHIN IBM	4-1
4.1	Formation of Engineering and Technology Services (E&TS) Division.....	4-4
4.2	Two Cornerstones of IBM Modus Operandi	4-7
4.3	Technology Group Evolution.....	4-8
4.4	IBM First Mission of Technology Group.....	4-13
4.5	Post-Bubble Extinctions and New Business Models	4-15
5.	NEW MERCHANT MARKET MICROELECTRONICS STRATEGY.....	5-1
5.1	Engineering & Technology Services	5-1
5.2	Technology Enablement Sphere.....	5-3
5.3	Technology-For-Sale Business Model	5-3
5.4	Five Implications of the New Merchant Market Strategy	5-7

6.	SILICON INTEGRATION ENABLEMENT RANGE	6-1
6.1	Business View of Silicon Integration Capabilities	6-5
6.2	Technology/Manufacturing View of Silicon Integration Capabilities	6-10
6.3	Business Engagements Options.....	6-14
7.	TRANSFORMATION OF IBM'S MERCHANT MICROELECTRONICS BUSINESS (1993 TO 2004).....	7-1
7.1	Stages of TG Organizational Transformation	7-1
7.2	Mission of the New Merchant Market Business Model.....	7-6
7.3	Implications for Merchant Market Vendors	7-12
8.	MICROELECTRONICS BUSINESS—ORGANIZATIONAL STRUCTURE AND TRENDS	8-1
8.1	IBM Annual Planning and Execution Cycle Timeline.....	8-2
8.2	IBM Corporate Functional Structure	8-6
8.3	IBM Technology Group Organizational Structure	8-7
8.4	Overlay of Technology Group and IBM Research.....	8-23
9.	WORLDWIDE OPERATING LOCATIONS AND HEADCOUNT	9-1
9.1	Semiconductor Manufacturing Locations.....	9-1
9.2	Interconnect Manufacturing Locations	9-4
9.3	Asset Divestitures While Retaining Business Control.....	9-9
9.4	Development and Design Centers	9-13
9.5	Worldwide Technology Group Headcount	9-15
10.	BUSINESS PERFORMANCE AND TRENDS	10-1
10.1	Business Consulting Services Formation	10-5
10.2	Engineering and Technology Services Formation and Role	10-8
10.3	Implications of IBM Services Pyramid.....	10-15
10.4	Intellectual Property and Custom Development Business.....	10-24
10.5	Hardware Business Revenues.....	10-26
10.6	Customer (Client) Base.....	10-38
10.7	Manufacturing Capabilities.....	10-47
11	ABOUT THE PETROV GROUP.....	11-1
11.1	Petrov Group.....	11-1
11.2	Our Work.....	11-4

MICROELECTRONICS BUSINESS OF IBM

ENABLING MERCHANT PLAYERS TO COMPETE

LIST OF FIGURES

1.	Technology Group Functional Structure within IBM	4-2
2.	Extended Reach of the IBM Services Machine	4-6
3.	Transformation of IBM TG Merchant Business (1992-2003).....	4-9
4.	IBM's New Semiconductor Strategy: Technology-for-Sale	5-2
5.	IBM Silicon Integration Capabilities: Technology vs. Business View	6-2
6.	Silicon Integration Wheel™	6-3
7.	IBM Silicon Integration Engagement Sphere.....	6-4
8.	Blueprint of IBM Silicon Integration Business Engagement	6-15
9.	Transformation of IBM Merchant Business	7-2
10.	IBM New Technology-for-Sale: Inside and Outside MPU Universes	7-10
11.	IBM Annual Business Planning and Execution Cycle.....	8-3
12.	IBM Technology Group Organization Structure (January 2004)	8-8
13.	Microelectronics Division Organizational Formation (June 2002)	8-9
14.	Engineering & Technology Services (T&TS), July 2003.....	8-11
15.	E&TS Division Organizational Formation (June 2003)	8-12
16.	IBM Global Semiconductor and Interconnect Manufacturing Organization (July 2002).....	8-13
17.	COT & Complementary Products Business Formation (July 2002)	8-17
18.	The New Integrated Chip Design and Manufacturing Space	8-35
19.	Two IC Design Mega Trends in the Sub-90 nm Semiconductor Industry	8-36
20.	IBM WW Interconnect Products and Services Operations (July 2003).....	9-6
21.	IBM Technology Group Headcount (12/2003).....	9-17
22.	IBM External Revenue Trends (1993 to 2003).....	10-2
23.	IBM Service Practices (E&TS) versus Silicon Integration	10-14
24.	IBM Technology Business Transformation for the On Demand Era	10-16
25.	IBM Implementation of the Shorten/Eliminate/Integrate Doctrine	10-20
26.	IBM IP and Custom Development Income	10-25
27.	IBM Hardware Sandwich Structure and Revenue Content	10-28
28.	Profile of the IBM Hardware Sandwich Revenue Content.....	10-34
29.	Technology/Manufacturing View of IBM HW Sandwich Resources	10-36
30.	IBM Technology Business Customer Base Transformation.....	10-43
31.	IBM Worldwide Semiconductor Wafer Fabs (July 2003)	10-49
32.	Wafer Production Capacity and Utilization (June 2003).....	10-30